

Helping Customers Innovate, Improve & Grow

Table 1. Electrical Performance								
Parameter	Symbol	Min.	Тур	Max	Units			
Nominal Frequency	F _{NOM}	8.000		100.000	MHz			
Mode		Fundan	nental or 3rd Ov	ertone				
Operating Temperature Range	T _{OP}	0/70, -	°C					
Stability Over T _{OP} ¹	F _{STAB}	±10		±100	ppm			
Frequency Tolerance ²	F _{TOL}		±10	±20	ppm			
Load Capacitance	C _L	6		32	pF			
Shunt Capacitance	C _o			5	pF			
Drive Level			10	100	uW			
Aging / 1st year (at 25 °C)	F _{AGE}			±5	ppm			
Insulation Resistance		500			MOhm			
Storage Temperature	T _{sto}	-40		90	°C			
		eries Resistance						
Crystal Frequency 8.000MHz-10.000MHz 10.001MHz-14.000MHz 14.001MHz-20.000MHz 20.001MHz-40.000MHz 40.000MHz-100.000MHz, 3rd Overtone	ESR			60 50 40 30 80	Ohm			

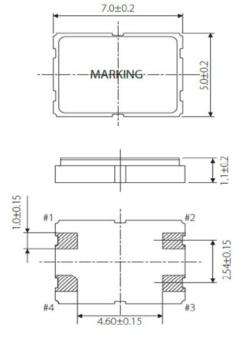
Notes:

- 1. Referenced to the Frequency at 25 °C.
- 2. Frequency measured at 25 °C \pm 3 °C.

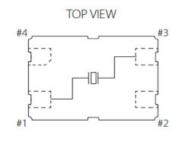
Product is compliant to RoHS directive and fully compatible with lead free assembly.



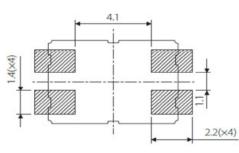
Package Drawing



Botttom View



RECOMMENDED LAND PATTERN



All Dimensions in mm

Part Marking:

XXMXXX

YYWWC

.XXMXXX = Frequency

YY = Year

WW= Week

C = Manufacuting Location

Alternative Marking

VXC4-XXX

XXMXX YMC

VCX4-XXX = Ordering Code

XXMXXX = Frequency

Y = Year

M = Month (A = Jan

C = Manufacturing Location

Table 2. Pinout							
Pin	n Function						
1	Crystal						
2	Connected to cover (Connect to GND						
3	Crystal						
4	Connected to cover (Connect to GND)						

Table 2. Environmental Compliance							
Parameter	Conditions						
Mechanical Shock	MIL-STD-883, Method 2002, Condition B						
Mechanical Vibration	MIL-STD-883, Method 2007, Condition A						
Temperature Cycle	MIL-STD-883, Method 1010, Condition B						
Solderability	MIL-STD-202-210, Condition B						
Gross and Fine Leak	MIL-STD-883, Method 1014						
Altitude	MIL-STD-883, Method 1001, Condition B						
Moisture Sensitivity Level	MSL 1						
Contact Pads	Gold (0.2 um min) over Nickel						
Weight	116 mg						

Reliability & IR Compliance

Solderprofile:

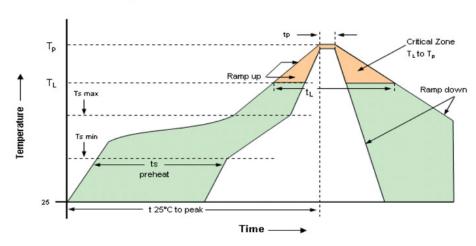
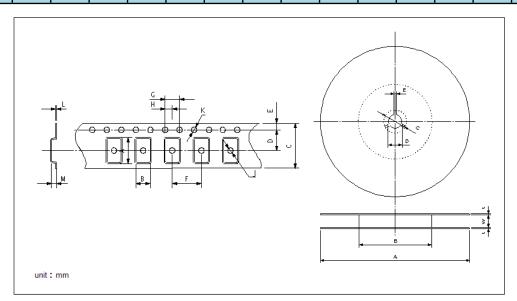


Table 3: Reflow Profile								
Parameter	Symbol	Value						
PreHeat Time Ts-min Ts-max	t _s	60 sec Min, 260 sec Max 150°C 200°C						
Ramp Up	R_{UP}	3 °C/sec Max						
Time Above 217 °C	$t_{_{L}}$	60 sec Min, 150 sec Max						
Time To Peak Temperature	T_{AMB-P}	480 sec Max						
Time at 260 °C	t _p	30 sec Max						
Ramp Down	R _{DN}	6 °C/sec Max						

Pads are Au over Ni and compatible with either SnPb or Pb free attachment. MSL: 1

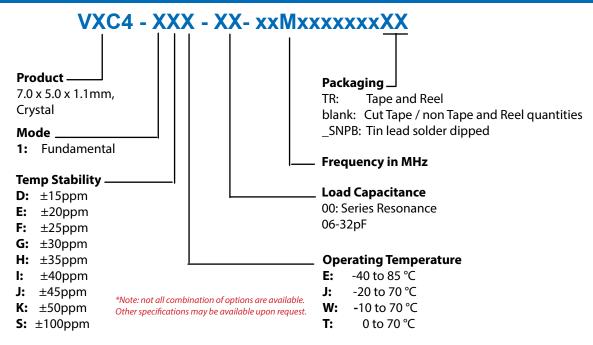
Tape & Reel

Table	Table 4. Tape and Reel Dimensions (mm)																	
Tape							Reel											
Α	В	С	D	Е	F	G	Н	J	К	L	М	Α	В	С	D	Е	W	Т
7.3	5.3	16.0	7.5	1.75	8.0	4.0	2.0	1.5	1.5	0.3	1.9	180	60	21.0	13.0	2.0	16.5	1.5



1K pieces per reel

Ordering Information



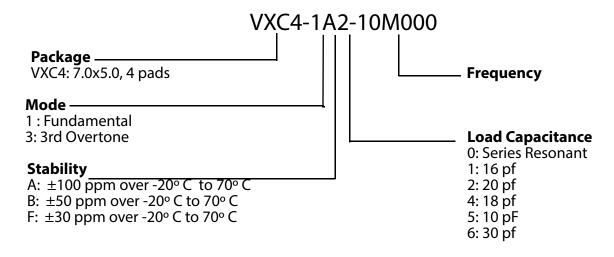
Example:

VXC4-1EE-12-25M000000TR Tape and Reel
VXC4-1EE-12-25M0000000 Cut Tape
VXC4-1EE-12-25M0000000_SNPB Tin lead solder dipped

Revision History

Revision Date	Approved	Description
August 30, 2016	RC	Initial datasheet for factory approval and release to customer.
February 06, 2018	FB	Add device marking, update to Microsemi
Ausust 10, 2018	FB	Update logo and ordering information
June 09, 2019	FB	Update logo and contact information, add Table 2 Environmental compliance, change "SNPBDIP" to "SNPB"
April 30, 2020	FB	Add tape and reel ordering option

Previous Ordering Information for Reference Only Do Not Use to Build a New Part Number



The ordering codes for the VXC4 were changed in 2016. If you had ordered a specific code based off this ordering method, it is still available for purchase under the old code however no new part numbers will be created using this system.

Due to the change in the 8th character from numeric to alphabetic, there is no opportunity for overlap between the two ordering methods.

Contact Information

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